Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.020”**

**‘”**

**.020”**

**.015”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: .015” X .015”**

**Backside Potential: Cathode**

**Mask Ref: ZCB**

**APPROVED BY: DK DIE SIZE .020” X .020” DATE: 5/9/23**

**MFG: SPRAGUE/ALLEGRO THICKNESS .007” P/N: 1N5238, THZ8R7A05**

**DG 10.1.2**

#### Rev B, 7/19/02